

METHOD AND APPARATUS FOR ETCHING A SEMICONDUCTOR DIE

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Abstract

5 A method and apparatus for etching a semiconductor die are disclosed whereby flowing an etchant material across an inactive thereof thins the semiconductor die. In one embodiment, the etchant includes a mixture of nitric acid, hydrofluoric acid, and acetic acid and turbulently flows from one edge of the semiconductor die, across the inactive surface of the semiconductor die, to an opposing edge of the semiconductor die.